

## REMARKS/ARGUMENTS

In the Office Action mailed October 1, 2007, claims 1 – 8 were rejected. Additionally, claims 1, 3, 5, and 8 were objected to. In response, Applicants have amended claims 1, 4, 5, and 8 and added new claims 9 and 10. Applicants hereby request reconsideration of the application in view of the amended claims and the below-provided remarks.

For reference, claims 1, 4, 5, and 8 have been amended to overcome the informalities noted in the Office action. Additionally, claims 4 and 5 have been amended to recite “the *semiconductor chip*” as recited in the respective preambles.

### Response to Claim Rejections

Claims 1 – 8 are rejected under 35 U.S.C. 102(b) as being anticipated by Holloway et al. (U.S. Pat. No. 6,183,131, hereinafter Holloway). However, Applicants respectfully submit that these claims are not anticipated by Holloway for the reasons provided below.

#### Claim 1

Claim 1 has been amended to particularly point out that “the second temperature point is a *virtual temperature point*.” Support for the amendment is found in Applicants’ specification at, for example, paragraphs [0008] and [0009] (U.S. Pat. Pub. No. 2007/0195858 A1). As amended, claim 1 recites:

“Arrangement on a semiconductor chip for calibrating a temperature setting curve having

a signal generation unit for providing a first signal, which is proportional to an actual temperature of the chip, whereby a signal offset is creatable by the signal generation unit, which is combined with the first signal *defining a second signal*; and

a temperature extraction unit receiving the first signal and the second signal for calculating a first temperature point based on the first signal and a second temperature point based on the second signal, *wherein the second temperature point is a virtual temperature point*.” (emphasis added)

Applicants assert that claim 1 is not anticipated by Holloway because Holloway does not disclose using a virtual temperature point to calibrate a temperature setting

curve, wherein the virtual temperature point is calculated from a signal that is a combination of a signal representative of an actual temperature and a signal offset.

Holloway discloses a technique for generating an ideal or nearly ideal temperature output signal to correct for reference voltage curvature, col. 5, lines 36 – 38. The technique involves modifying the reference voltage to be non-linear over a specific temperature range, col. 4, lines 38 – 39. While Holloway discloses a technique for generating an ideal or nearly ideal temperature output signal to correct for reference voltage curvature, Holloway does not disclose using a “virtual temperature point” to calibrate a temperature setting curve as recited in amended claim 1. In particular, Holloway does not disclose using a “virtual temperature point” to calibrate a temperature setting curve, wherein the virtual temperature point is calculated from a signal that is a combination of a signal representative of an actual temperature and a signal offset. Because Holloway does not disclose using a “virtual temperature point” to calibrate a temperature setting curve, wherein the virtual temperature point is calculated from a signal that is a combination of a signal representative of an actual temperature and a signal offset, Applicants assert that claim 1 is not anticipated by Holloway.

#### Independent Claim 4

Independent claim 4 has been amended to include similar limitations to claim 1. In view of the similarities between claim 4 and claim 1, Applicants assert that the remarks provided above in regard to claim 1 apply also to claim 4. Accordingly, Applicants respectfully assert that independent claim 4 is not anticipated by Holloway.

#### Dependent Claims 2, 3, and 5 – 8

Claims 2 and 3 are dependent on claim 1 and claims 5 – 8 are dependent on claim 4. Applicants respectfully assert that claims 2, 3, and 5 – 8 are allowable at least based on allowable base claims.

### New Claims 9 and 10

New claims 9 and 10 particularly point out that the second temperature point and the second virtual temperature do not exist in the semiconductor chip during calibration of the temperature setting curve. Support for new claims 9 and 10 is found in Applicants' specification at, for example, paragraphs [0008] and [0009] (U.S. Pat. Pub. No. 2007/0195858 A1). Applicants respectfully assert that claims 9 and 10 are not anticipated by Holloway because Holloway does not disclose the limitations of new claims 9 and 10.

### **CONCLUSION**

Applicants respectfully requests reconsideration of the claims in view of the amended claims, the new claims, and the remarks made herein. A notice of allowance is earnestly solicited.

At any time during the pendency of this application, please charge any fees required or credit any over payment to Deposit Account **50-3444** pursuant to 37 C.F.R. 1.25. Additionally, please charge any fees to Deposit Account **50-3444** under 37 C.F.R. 1.16, 1.17, 1.19, 1.20 and 1.21.

Respectfully submitted,

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